Absolute Maximum Ratings

Symbol	Conditions [1]	Values	Units
V_{CES}		600	V
V_{GES}		± 20	V
I_C	T_h = 25/80 °C	30 / 21	A
I_{CM}	t_p < 1 ms; T_h = 25/80 °C	60 / 42	A
$I_F = -I_C$	T_h = 25/80 °C	36 / 24	A
$I_{FM} = -I_{CM}$	t_p < 1 ms; T_h = 25/80 °C	72 / 48	A
T_j		– 40 ... + 150	°C
T_{stg}		– 40 ... + 125	°C
T_{sol}	Terminals, 10 s	260	°C
V_{isol}	AC, 1 min	2500	V

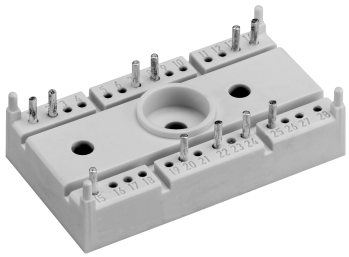
Characteristics

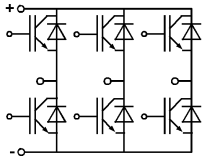
Symbol	Conditions [1]	min.	typ.	max.	Units
V_{CEsat}	I_C = 20 A; T_j = 25 (125) °C	–	1,8(1,9)	2,2(2,4)	V
$t_{d(on)}$	V_{CC} = 300 V; V_{GE} = ± 15 V	–	40	–	ns
t_r	I_C = 25 A, T_j = 125 °C	–	50	–	ns
$t_{d(off)}$	$R_{Gon} = R_{Goff}$ = 33 Ω	–	200	–	ns
t_f	inductive load	–	25	–	ns
$E_{on} + E_{off}$		–	2,2	–	mJ
C_{ies}	V_{CE} = 25 V; V_{GE} = 0 V, 1 MHz	–	1,6	–	nF
R_{thjh} [3]	per IGBT	–	–	1,4	K/W
Inverse Diode [2]					
$V_F = V_{EC}$	I_F = 25 A; T_j = 25 (125) °C	–	1,45(1,4)	1,7(1,75)	V
V_{TO}	T_j = 125 °C	–	0,85	0,9	V
r_T	T_j = 125 °C	–	22	32	mΩ
I_{RRM}	I_F = 25 A; V_R = 300 V	–	16	–	A
Q_{rr}	di_F/dt = – 500 A/µs	–	2	–	µC
E_{off}	V_{GE} = 0 V; T_j = 125 °C	–	0,25	–	mJ
R_{thjh} [3]	per Diode	–	–	1,7	K/W
Mechanical Data					
M1	mounting torque	–	–	2,5	Nm
w		–	30	–	g
Case			T 12		

SEMITOP® 3
IGBT Module

SK 25 GD 063

Preliminary Data





GD

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N channel, homogeneous silicon structure (NPT Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence

Typical Applications

- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS

[1] T_h = 25 °C, unless otherwise specified
[2] CAL = Controlled Axial Lifetime Technology (soft and fast recovery)
[3] Thermal resistance junction to heatsink

Cases → page 4

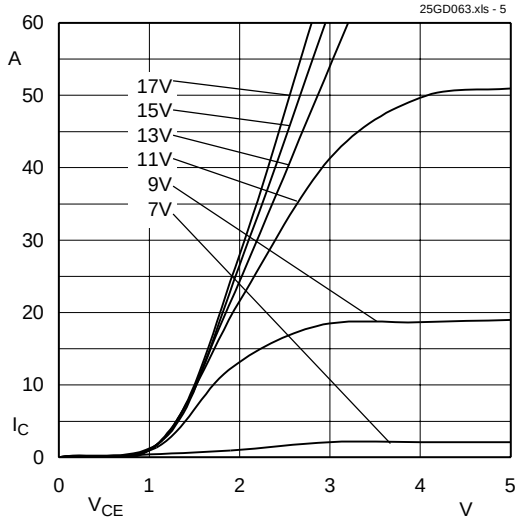


Fig. 5 Typ. output characteristic, t_p = 80 µs; 25 °C

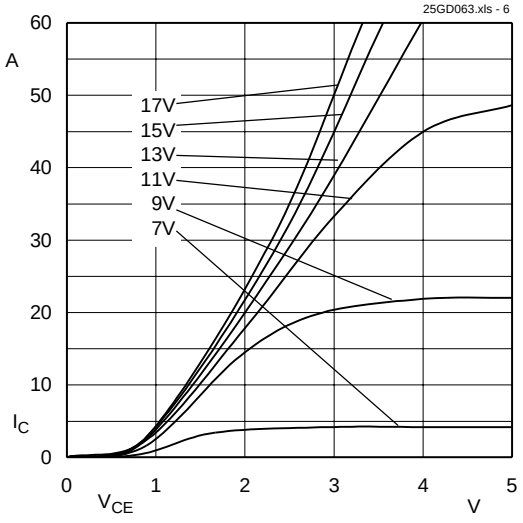


Fig. 6 Typ. output characteristic, t_p = 80 µs; 125 °C

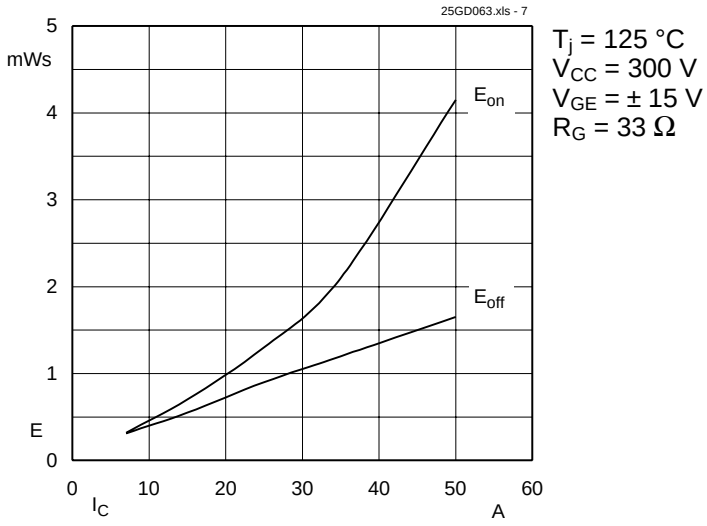


Fig. 7 Turn-on /-off energy = f (I_C)

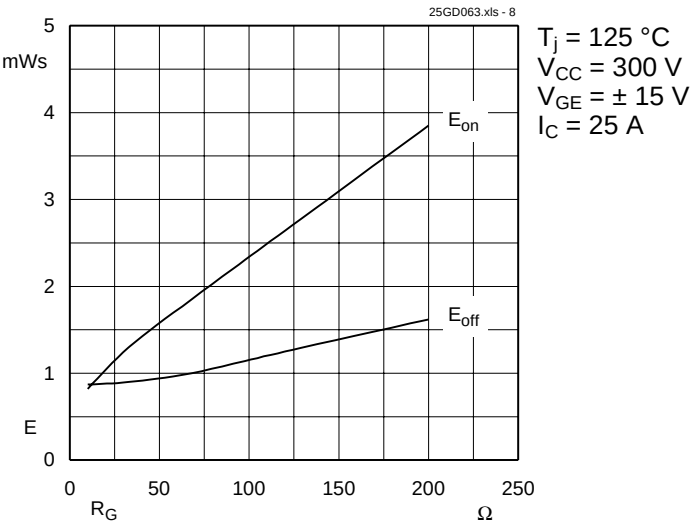


Fig. 8 Turn-on /-off energy = f (R_G)

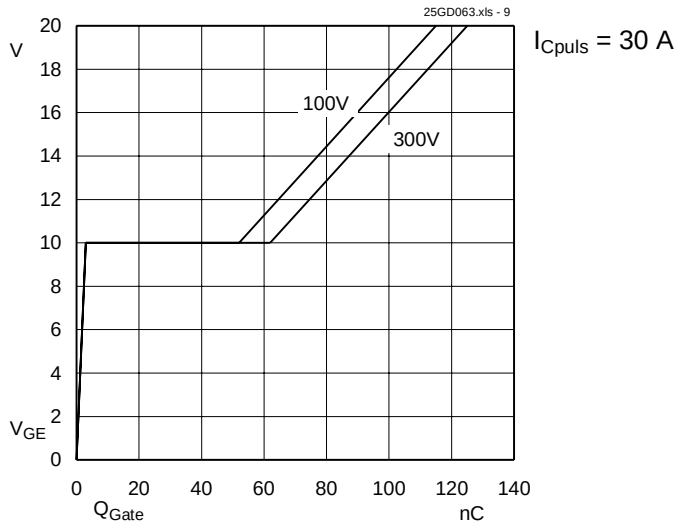


Fig. 9 Typ. gate charge characteristic

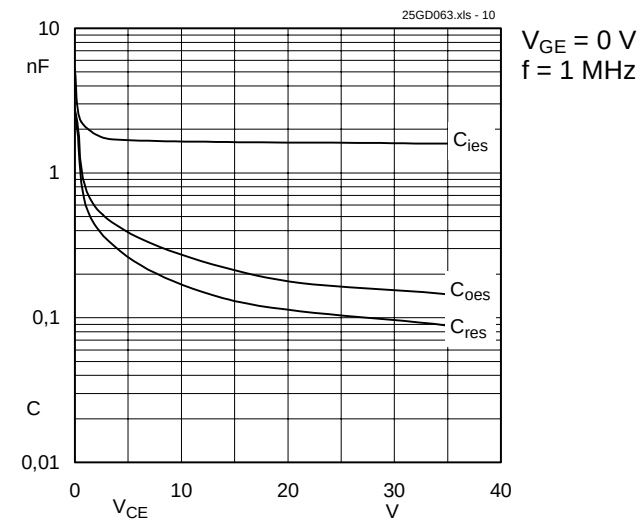


Fig. 10 Typ. capacitances vs. V_{CE}

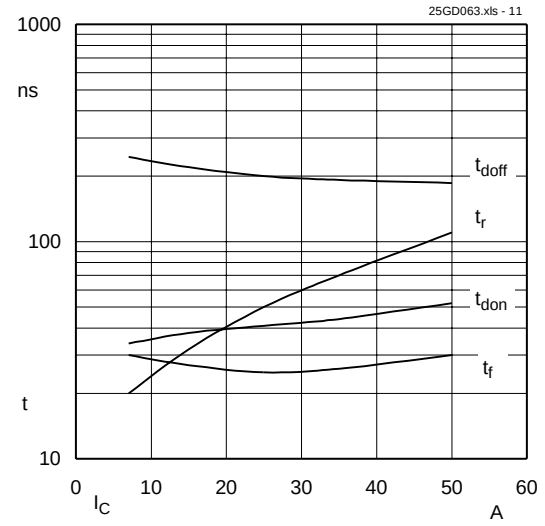


Fig. 11 Typ. switching times vs. I_C

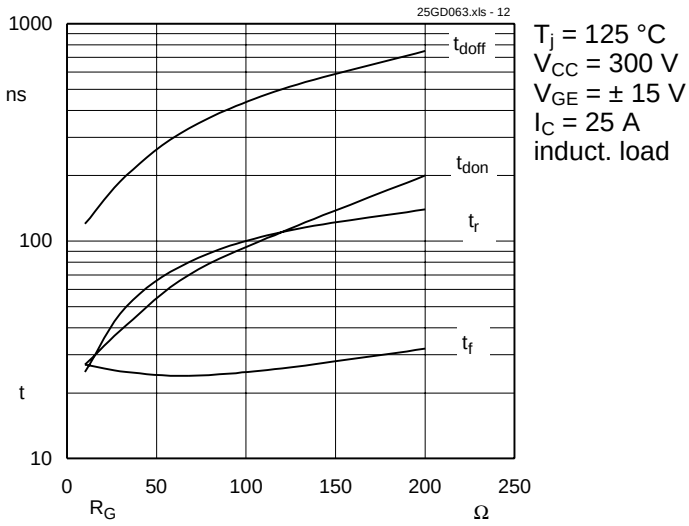


Fig. 12 Typ. switching times vs. gate resistor R_G

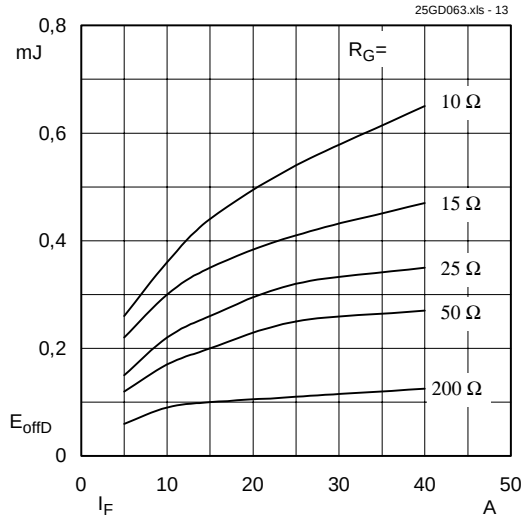


Fig. 13 Diode turn-off energy dissipation per pulse

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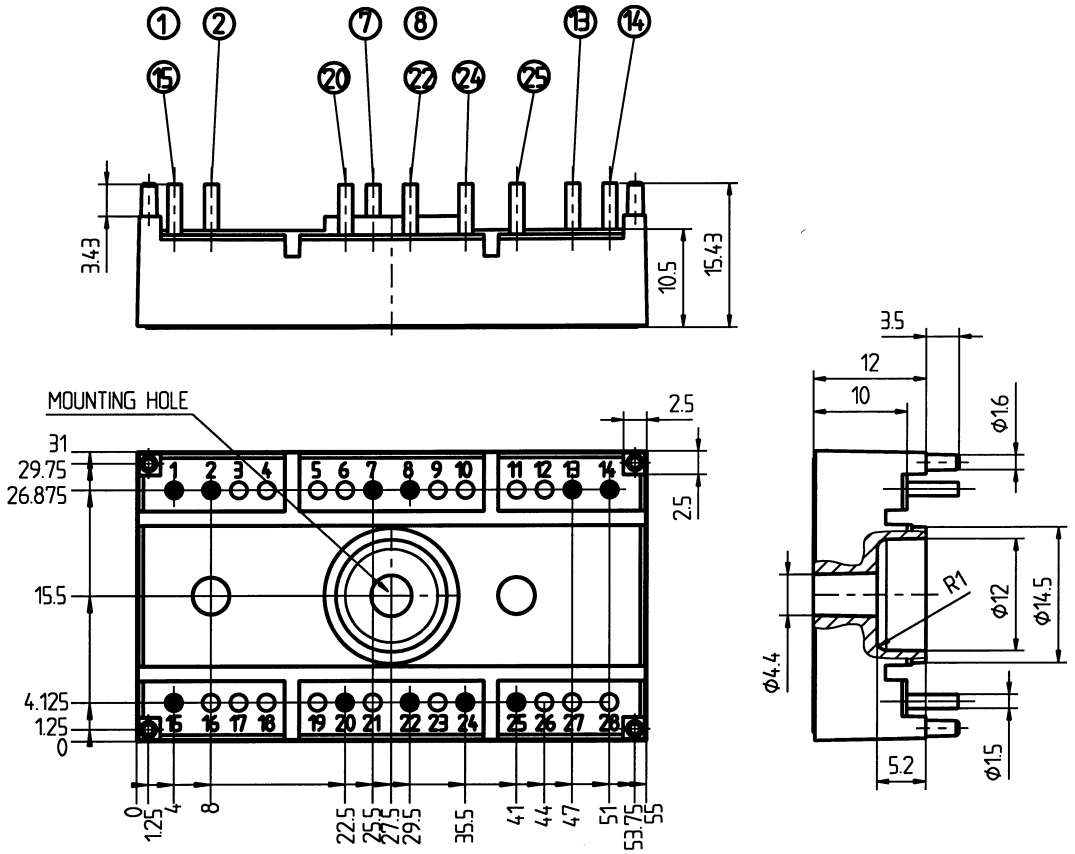

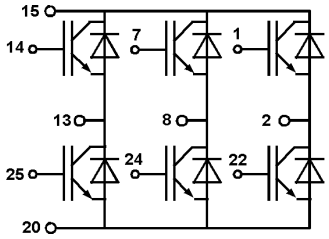

Dimensions in mm

